Motorola Part Numbers Affected:
XPC7400RX400PK
XPC7400RX450PK
XPC7400RX500PK

Application-Specific Information

MPC7400 Part Number Specification

This document describes part number specific changes to recommended operating conditions and revised electrical specifications, as applicable, from those described in the general *MPC7400 Hardware Specifications*.

Specifications provided in this Part Number Specification supersede those in the *MPC7400 Hardware Specifications* dated 9/99 (order #: MPC7400EC/D) for these part numbers only; specifications not addressed herein are unchanged. This document is frequently updated, refer to the website at http://www.mot.com/SPS/PowerPC/ for the latest version.

Note that headings and table numbers in this data sheet are not consecutively numbered. They are intended to correspond to the heading or table affected in the general hardware specification.

Part numbers addressed in this document are listed in Table A. For more detailed ordering information see Table B.

Table A. Part Numbers Addressed by this Data Sheet

Motorola Part Number	Operating Conditions			Significant Differences from Hardware Specification
	CPU Frequency	Vdd	T_J (°C)	
XPC7400RX400PK	400 MHz	2.15V±50mV	0 to 65	Modified Voltage & Temperature Specification to achieve 400Mhz frequency
XPC7400RX450PK	450 MHz	2.15V±50mV	0 to 65	Modified Voltage & Temperature Specification to achieve 450Mhz frequency
XPC7400RX500PK	500 MHz	2.15V±50mV	0 to 65	Modified Voltage & Temperature Specification to achieve 500Mhz frequency

Note: The X prefix in a Motorola PowerPC part number designates a “Pilot Production Prototype” as defined by Motorola SOP 3-13. These are from a limited production volume of prototypes manufactured, tested and Q.A. inspected on a qualified technology to simulate normal production. These parts have only preliminary reliability and characterization data. Before pilot production prototypes may be shipped, written authorization from the customer must be on file in the applicable sales office acknowledging the qualification status and the fact that product changes may still occur while shipping pilot production prototypes

Errata

This section summarizes design defects or errors (errata) that are known to exist for these parts. There may be additional errata that are not known or are not yet documented here which may cause the part to deviate from the functional description provided in the *MPC7400 RISC Microprocessor User’s Manual* (order # MPC7400UM/AD Rev 0). Refer to the website at http://www.mot.com/SPS/PowerPC/ for the latest version of this Part Number Specification or to your local Motorola sales office for later and/or more detailed description of the errata.

The known errata as of the date of this document are summarized below.

#	Problem	Description	Impact	Work-Around
1	Incorrect value was written to the MSR after running POR ABIST	When running ABIST after POR, the renames remained valid causing MSR to be updated with the incorrect value.	Running ABIST after POR	Insert an ISYNC instruction at the interrupt vector 0xFFF0_0100

#	Problem	Description	Impact	Work-Around
2	Not all GPRs and FPRs are initialized after ABIST	Not all GPRs and FPRs are initialized after ABIST due to invalid instructions in the instruction buffers.	GPRs and FPRs may not be initialized during ABIST if the contents of the instruction buffers can be decoded to non-zero GPR or FPR destination addresses.	None
3	Asserting TEA and ARTRY together may cause loss of data	Asserting TEA and ARTRY together in the first cycle of the snoop response window may cause loss of iside data.	Any system that permits the aggressive timing of TEA in the first cycle of the snoop response window.	Delay assertion of TEA until the second cycle of the snoop response window or later.
4	Incorrect condition code on mismatched LWARX/STWCX pair	A STWCX instruction may be performed without setting the condition code if the store hits in the L2 and the LWARX instruction that set the reservation is to another coherency granule.	Any code which uses mismatched LWARX/ STWCX address pairs	1. Avoid mismatched LWARX/STWCX address pairs, or 2. Turn off the L2
5	TLBSYNC may hang in the presence of a DST	The MPC7400 may not make forward progress if a DST has caused an MMU tablewalk, that MMU tablewalk was marked by a TLBIE instruction, and a TLBSYNC instruction is pipelined the cycle after the MMU tablewalk accesses the dL1 cache.	Any system which has an active DST engine while executing a TLBSYNC instruction in a privileged context	Insert a DSSALL instruction before a TLBSYNC instruction
6	Queueing six transactions to secondary bus may hang the system	Queueing six transactions from a single MAX processor could use all Data Transaction Queue resources and hang the system if forward progress cannot be made by allowing MAX to complete at least one outstanding transaction.	Any system which allows 6 outstanding transactions from a single processor and which has a secondary bus with characteristics as detailed in full description.	1. Limit the number of outstanding transactions from a secondary bus to 5 in system logic, or 2. Mark the memory space on the secondary bus as guarded and avoid DST(ST)(T) and LMW instructions.

1.2 General

This section summarizes changes to the features of the MPC7400 described in the *MPC7400 Hardware Specifications*.

- None.

1.4.1 DC Electrical Characteristics

Table 3 provides the recommended operating conditions for the MPC7400 part numbers described herein.

Table 3. Recommended Operating Conditions

Characteristic	Symbol	Recommended Value	Unit
Core supply voltage	Vdd	2.15V±50mV	
PLL supply voltage	AVdd	2.15V±50mV	
L2 DLL supply voltage	L2AVdd	2.15V±50mV	

Table 3. Recommended Operating Conditions (Continued)

Characteristic		Symbol	Recommended Value	Unit
Processor bus supply voltage	BVSEL = 0	OVdd	1.8V±100mV	V
	BVSEL = $\overline{\text{HRESET}}$	OVdd	2.5V±100mV	V
	BVSEL = 1	OVdd	3.3V±165mV	V
L2 bus supply voltage	L2VSEL = 0	L2OVdd	1.8V±100mV	V
	L2VSEL = $\overline{\text{HRESET}}$	L2OVdd	2.5V±100mV	V
	L2VSEL = 1	L2OVdd	3.3V±165mV	V
Input voltage	Processor bus	V_{in}	GND to OVdd	V
	L2 Bus	V_{in}	GND to L2OVdd	V
	JTAG Signals	V_{in}	GND to OVdd	V
Die-junction temperature		T_j	0-65	°C

Note: These are the recommended and tested operating conditions. Proper device operation outside of these conditions is not guaranteed.

Table 7 provides the power consumption for the MPC7400 part at the frequencies described herein.

Table 7. Power Consumption for MPC7400

	Processor (CPU) Frequency	Processor (CPU) Frequency	Processor (CPU) Frequency	Unit	Notes
	400Mhz	450Mhz	500Mhz		
Full-On Mode					
Typical	7.56	8.51	9.45	W	1, 3
Maximum	15.1	17.0	18.9	W	1, 2, 4
Doze Mode					
Maximum	6.7	7.5	8.3	W	1, 2
Nap Mode					
Maximum	2.7	3.0	3.3	W	1, 2
Sleep Mode					
Maximum	2.7	3.0	3.3	W	1, 2
Sleep Mode—PLL and DLL Disabled					
Typical	600	600	600	mW	1, 3
Maximum	1.0	1.0	1.0	W	1, 2

Notes:
See General hardware specification
4. These values are with Altivec. Without Altivec, estimate a 25% decrease.

1.4.2.1 Clock AC Specifications

Table 8 provides the additional clock AC timing specifications described in this Part Number Specification. Refer to the MPC7400

Hardware Specification for the remaining frequencies.

Table 8. Clock AC Timing Specifications

At recommended operating conditions (See Table 3)

Characteristic	Symbol	400 MHz		450 MHz		500MHz		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Processor frequency	f_{core}	350	400	350	450	350	500	MHz	
VCO frequency	f_{VCO}	700	800	700	900	700	1000	MHz	
SYSCLK frequency	f_{SYSCLK}	33	100	33	100	33	100	MHz	1
SYSCLK cycle time	t_{SYSCLK}	10	30	10	30	10	30	ns	
SYSCLK rise and fall time	t_{KR} & t_{KF}	—	1.0	—	1.0	—	1.0	ns	2
		—	0.5	—	0.5	—	0.5	ns	3
SYSCLK duty cycle measured at OVdd/2	t_{KHKL}/t_{SYSCLK}	40	60	40	60	40	60	%	4
SYSCLK jitter		—	±150	—	±150	—	±150	ps	5
Internal PLL relock time		—	100	—	100	—	100	µs	6

Notes:
See General hardware specification.

1.4.2.2 Processor Bus AC Specifications

Table 9 provides the processor bus AC timing specifications for the MPC7400 part described in this Part Number Specification.

Table 9. Processor Bus AC Timing Specifications[1]

At Vdd=AVdd=2.15V±50mV; 0 ≤ Tj ≤ 65°C, OVdd = 3.3V±165mV or OVdd = 2.5V±100mV or OVdd=1.8V±100mV

Parameter	Symbol	400, 450, 500 Mhz		Unit	Notes
		Min	Max		
Mode select input setup to $\overline{\text{HRESET}}$	t_{MVRH}	8	—	t_{sysclk}	2,3,4,5
$\overline{\text{HRESET}}$ to mode select input hold	t_{MXRH}	0	—	ns	2,3,5
Setup Times:				ns	10
Address/Transfer Attribute	t_{AVKH}	1.4	—		6
Transfer Start ($\overline{\text{TS}}$)	t_{TSVKH}	1.4	—		—
Data/Data Parity	t_{DVKH}	1.4	—		7
ARTRY/SHD0/SHD1	t_{ARVKH}	1.4	—		—
All Other Inputs	t_{IVKH}	1.4	—		8
Input Hold Times:				ns	11
Address/Transfer Attribute	t_{AXKH}	0	—		6
Transfer Start ($\overline{\text{TS}}$)	t_{TSXKH}	0	—		—
Data/Data Parity	t_{DXKH}	0	—		7
ARTRY/SHD0/SHD1	t_{ARXKH}	0	—		—
All Other Inputs	t_{IXKH}	0	—		8
Valid Times:				ns	12
Address/Transfer Attribute	t_{KHAV}	—	3.0		6
$\overline{\text{TS}}$, $\overline{\text{ABB}}$, $\overline{\text{DBB}}$	t_{KHTSV}	—	3.0		—
Data	t_{KHDV}	—	3.5		7
Data Parity	t_{KHDPV}	—	3.5		7
ARTRY/SHD0/SHD1	t_{KHARV}	—	2.3		—
All Other Outputs	t_{KHOV}	—	3.0		9
Output Hold Times:				ns	13
Address/Transfer Attribute	t_{KHAX}	0.75	—		6
$\overline{\text{TS}}$, $\overline{\text{ABB}}$, $\overline{\text{DBB}}$	t_{KHTSX}	0.75	—		—
Data/Data Parity	t_{KHDX}	0.6	—		7
ARTRY/SHD0/SHD1	t_{KHARX}	0.75	—		—
All Other Outputs	t_{KHOX}	0.75	—		9

Table 9. Processor Bus AC Timing Specifications[1] (Continued)

At Vdd=AVdd=2.15V±50mV; 0 ≤ Tj ≤ 65°C, OVdd = 3.3V±165mV or OVdd = 2.5V±100mV or OVdd=1.8V±100mV

Parameter	Symbol	400, 450, 500 Mhz		Unit	Notes
		Min	Max		
SYSCLK to Output Enable	t_{KHOE}	0.5	—	ns	14
SYSCLK to Output High Impedance (all except TS, ABB/AMON(0), ARTRY/SHD, DBB/DMON(0))	t_{KHOZ}	—	3.5	ns	15
SYSCLK to TS, ABB/AMON(0), DBB/DMON(0) High Impedance after precharge	t_{KHABPZ}	—	1.0	t_{sysclk}	4,15, 16,17
Maximum Delay to ARTRY/SHD0/SHD1 Precharge	t_{KHARP}	—	1	t_{sysclk}	4,17
SYSCLK to ARTRY/SHD0/SHD1 High Impedance After Precharge	t_{KHARPZ}	—	2	t_{sysclk}	4,17

Notes:
1. These values apply for all valid processor bus and L2 bus ratios. The values do not include I/O Supply Power (OVdd and L2OVdd) or PLL/DLL supply power (AVdd and L2AVdd). OVdd and L2OVdd power is system dependent, but is typically <10% of Vdd power. Worst case power consumption for AVdd = 15 mw and L2AVdd = 15 mW.
2. Maximum power is measured at Vdd = 2.2V while running an entirely cache-resident, contrived sequence of instructions which keep the execution units, including AltiVec, maximally busy.
3. Typical power is an average value measured at Vdd = AVdd = L2AVdd = 2.15V, OVdd = L2OVdd = 3.3V in a system while running a codec application that is AltiVec intensive.

1.4.2.3 L2 Clock AC Specifications

Table 10 provides the L2CLK Output AC Timing Specifications for the MPC7400 part described in this Part Number Specification.

Table 10. L2CLK Output AC Timing Specifications

At recommended operating conditions (See Table 3)

Parameter	Symbol	400 MHz		450 MHz		500 MHz		Unit	Notes
		Min	Max	Min	Max	Min	Max		
L2CLK frequency	f_{L2CLK}	150	400	150	450	150	500	MHz	1
L2CLK cycle time	t_{L2CLK}	2.5	6.67	2.22	6.67	2.0	6.67	ns	
L2CLK duty cycle	t_{CHCL}/t_{L2CLK}	50		50		50		%	2
Internal DLL-relock time		640	—	640	—	640	—	L2CLK	4
DLL capture window			±200		±200		±200	ns	5

Notes:
See General hardware specification.

1.4.2.4 L2 Bus AC Specifications

Table 11 provides the L2 Bus Interface AC Timing Specifications for the frequencies described in this Part Number Specification.

Table 11. L2 Bus Interface AC Timing Specifications

At Vdd=AVdd=L2AVdd= 2.15V±50mV; 0 ≤ Tj ≤ 65°C, L2OVdd = 3.3V±165mV or L2OVdd = 2.5V±100mV or L2OVdd=1.8V±100mV

Parameter	Symbol	400 MHz		450 MHz		500 MHz		Unit	Notes
		Min	Max	Min	Max	Min	Max		
L2SYNC_IN rise and fall time	t_{L2CR} & t_{L2CF}	—	1.0	—	1.0	—	1.0	ns	1
Setup Times: Data and parity	t_{DVL2CH}	1.5	—	1.3	—	1.0	—	ns	2
Input Hold Times: Data and parity	t_{DXL2CH}	—	0.0	—	0.0	—	0.0	ns	2
Valid Times: All outputs when L2CR[14-15] = 00 All outputs when L2CR[14-15] = 01 All outputs when L2CR[14-15] = 10 All outputs when L2CR[14-15] = 11	t_{L2CHOV}	 - - - -	 2.5 3.0 3.5 4.0	 - - - -	 2.4 - - -	 - - - -	 2.3 - - -	ns	3,4
Output Hold Times All outputs when L2CR[14-15] = 00 All outputs when L2CR[14-15] = 01 All outputs when L2CR[14-15] = 10 All outputs when L2CR[14-15] = 11	t_{L2CHOX}	 0.4 1.0 1.4 1.8	 - - - -	 0.3 - - -	 - - - -	 0.2 - - -	 - - - -	ns	3
L2SYNC_IN to high impedance: All outputs when L2CR[14-15] = 00 All outputs when L2CR[14-15] = 01 All outputs when L2CR[14-15] = 10 All outputs when L2CR[14-15] = 11	t_{L2CHOZ}	 - - - -	 2.0 2.5 3.0 3.5	 - - - -	 2.0 2.5 3.0 3.5	 - - - -	 2.0 2.5 3.0 3.5	ns	
Notes: See General Hardware Specification									

1.10 Ordering Information

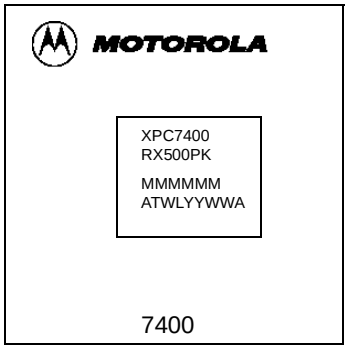
Table B provides the ordering information for the MPC7400 part described in this Part Number Specification..

Table B. Ordering Information for the MPC7400 Microprocessor

Package Type	Device Rev	Process	Mask Code	CPU Frequency (MHz)	Motorola Part Number
360 CBGA	2.9	HIP5P	89J87W or 89K62D	400MHz	XPC7400RX400PK
				450MHz	XPC7400RX450PK
				500MHz	XPC7400RX500PK

1.10.1 Part Marking

Parts are marked as the example shown in Figure A.



BGA

Notes:

MMMMMM is the 6-digit mask number

ATWLYYWWA is the traceability code

CCCCC is the country of assembly (this space is left blank if parts are assembled in the United States)

Figure A. Motorola Part Marking for BGA Device